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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA, FC (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb5d4f31i5n

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Feature	Description
Configuration	 Tamper protection-comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Partial and dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8, x16, and x32 (Arria V GZ) configuration options Remote system upgrade

Arria V Device Variants and Packages

Table 3: Device Variants for the Arria V Device Family

Variant	Description
Arria V GX	FPGA with integrated 6.5536 Gbps transceivers that provides bandwidth, cost, and power levels that are optimized for high-volume data and signal-processing applications
Arria V GT	FPGA with integrated 10.3125 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for cost-sensitive data and signal processing applications
Arria V GZ	FPGA with integrated 12.5 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for high-performance and cost-sensitive data and signal processing applications
Arria V SX	SoC with integrated ARM-based HPS and 6.5536 Gbps transceivers
Arria V ST	SoC with integrated ARM-based HPS and 10.3125 Gbps transceivers

Arria V GX

This section provides the available options, maximum resource counts, and package plan for the Arria V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

Related Information

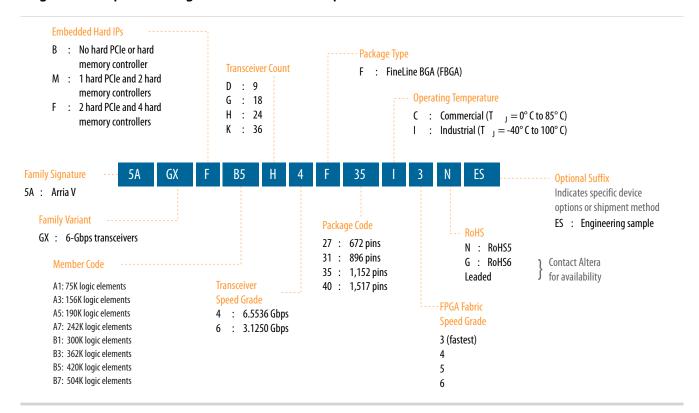
Altera Product Selector

Provides the latest information about Altera products.



Available Options

Figure 1: Sample Ordering Code and Available Options for Arria V GX Devices



Maximum Resources

Table 4: Maximum Resource Counts for Arria V GX Devices

Poso	Resource				Me	mber Code			
neso	urce	A1	А3	A 5	A7	B1	В3	B5	В7
Logic I (LE) (F	Elements ()	75	156	190	242	300	362	420	504
ALM		28,302	58,900	71,698	91,680	113,208	136,880	158,491	190,240
Registe	er	113,208	235,600	286,792	366,720	452,832	547,520	633,964	760,960
Mem	M10K	8,000	10,510	11,800	13,660	15,100	17,260	20,540	24,140
ory (Kb)	MLAB	463	961	1,173	1,448	1,852	2,098	2,532	2,906
Variab precisi Block	le- on DSP	240	396	600	800	920	1,045	1,092	1,156
18 x 18 Multip		480	792	1,200	1,600	1,840	2,090	2,184	2,312
PLL		10	10	12	12	12	12	16	16



Resource					Me	mber Code			
nesc	uice	A1	А3	A 5	A7	B1	В3	B5	В7
6 Gbps Transc		9	9	24	24	24	24	36	36
GPIO ⁽	(3)	416	416	544	544	704	704	704	704
LVD S	Transmi tter	67	67	120	120	160	160	160	160
3	Receiver	80	80	136	136	176	176	176	176
PCIe I Block	Hard IP	1	1	2	2	2	2	2	2
Hard I Contro	Memory oller	2	2	4	4	4	4	4	4

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code		72 mm)	F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	_	_	_	_
A3	336	9	416	9	_	_	_	_
A5	336	9	384	18	544	24	_	_
A7	336	9	384	18	544	24	_	_
B1	_	_	384	18	544	24	704	24
В3	_	_	384	18	544	24	704	24
B5	_	_	_	_	544	24	704	36
В7	_	_	_	_	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.



⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus[®] Prime software, the number of user I/Os includes transceiver I/Os.

Resource			Member Code						
Neso	ui ce	C 3	C 7	D3	D7				
Transceiver	6 Gbps ⁽⁴⁾	3 (9)	6 (24)	6 (24)	6 (36)				
Transcerver	10 Gbps ⁽⁵⁾	4	12	12	20				
GPIO ⁽⁶⁾		416	544	704	704				
LVDS	Transmitter	68	120	160	160				
LVD3	Receiver	80	136	176	176				
PCIe Hard IP Block		1	2	2	2				
Hard Memor	y Controller	2	4	4	4				

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

• Transceiver Architecture in Arria V Devices

Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Memb		F672 (27 mm)		F896 (31 mm)			F1152 (35 mm)			F151 (40 mr		
er Code		ХС	VR		ХС	VR		ХС	VR		2	KCVR
	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	_	_	_	_	_	_
C7	_	_	_	384	6 (18)	8	544	6 (24)	12	_	_	_
D3	_	_	_	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	_	_	_	_	_	_	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps



⁽⁴⁾ The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.

⁽⁵⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

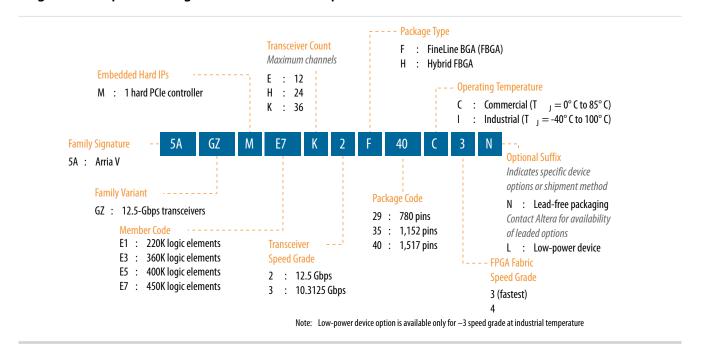
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code						
nesource	E1	E 3	E 5	E 7			
Logic Elements (LE) (K)	220	360	400	450			
ALM	83,020	135,840	150,960	169,800			
Register	332,080	543,360	603,840	679,200			



Pose	Resource		Me	ember Code	
nesc	ruice	E1	E 3	E 5	E 7
Memory	M20K	11,700	19,140	28,800	34,000
(Kb)	MLAB	2,594	4,245	4,718	5,306
Variable-pred	cision DSP Block	800	1,044	1,092	1,139
18 x 18 Multi	plier	1,600	2,088	2,184	2,278
PLL		20	20	24	24
12.5 Gbps Tr	ansceiver	24	24	36	36
GPIO ⁽⁷⁾		414	414	674	674
LVDS	Transmitter		99	166	166
LVDS	Receiver	108	108	168	168
PCIe Hard IF	Block	1	1	1	1

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 9: Package Plan for Arria V GZ Devices

Member Code	H780 (33 mm)			152 mm)	F1517 (40 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
E1	342	12	414	24	_	_	
E3	342	12	414	24	_	_	
E5	_	_	534	24	674	36	
E7	_	_	534	24	674	36	

Arria V SX

This section provides the available options, maximum resource counts, and package plan for the Arria V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



⁽⁷⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Poss	ource	1	Member Code
neso	ruice	В3	B5
FPGA PLL		14	14
HPS PLL		3	3
6 Gbps Transceiver		30	30
FPGA GPIO ⁽⁸⁾		540	540
HPS I/O		208	208
LVDS	Transmitter	120	120
LVDS	Receiver	136	136
PCIe Hard IP Block		2	2
FPGA Hard Memory	Controller	3	3
HPS Hard Memory C	Controller	1	1
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 11: Package Plan for Arria V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

	F896			F1152			F1517		
Member Code	(31 mm)			(35 mm)			(40 mm)		
Code	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
В3	250	208	12	385	208	18	540	208	30
B5	250	208	12	385	208	18	540	208	30

Arria V ST

This section provides the available options, maximum resource counts, and package plan for the Arria V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Poso	ource	Member Code			
nesu	raice	D3	D5		
FPGA GPIO ⁽¹⁰⁾		540	540		
HPS I/O		208	208		
LVDS	Transmitter	120	120		
LVD3	Receiver	136	136		
PCIe Hard IP Block		2	2		
FPGA Hard Memory	PGA Hard Memory Controller		3		
HPS Hard Memory C	Controller	1	1		
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core		

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Transceiver Architecture in Arria V Devices
 Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 13: Package Plan for Arria V ST Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Memb	F896 (31 mm)			F1152 (35 mm)				F1517 (40 mm)				
er Code	FPGA	HPS	ХС	VR	FPGA	HPS	ХС	VR	FPGA	HPS		KCVR
11	GPIO	I/O	6 Gbps	10 Gbps	GPIO	I/O	6 Gbps	10 Gbps	GPIO	1/0	6 Gbps	10 Gbps
D3	250	208	12	6	385	208	18	8	540	208	30	16
D5	250	208	12	6	385	208	18	8	540	208	30	16



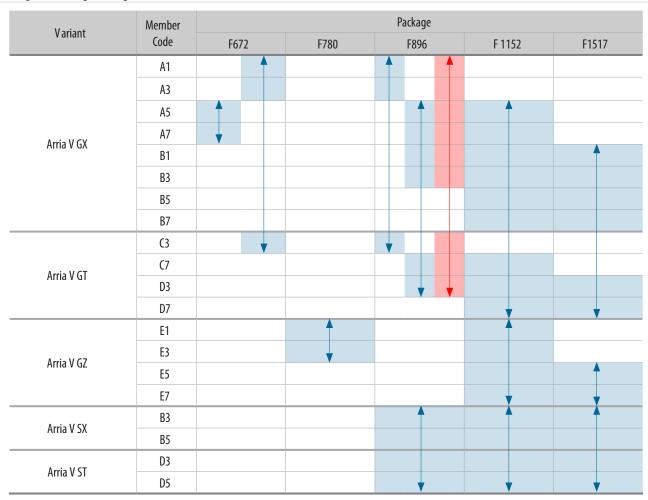
⁽⁹⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.



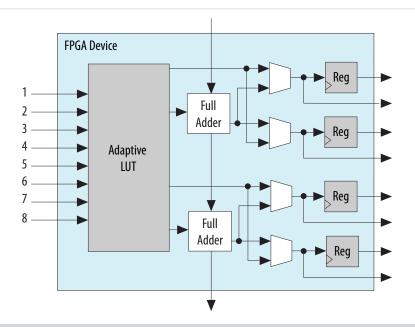
- Managing Device I/O Pins chapter, Quartus Prime Handbook Provides more information about vertical I/O migrations.
- Power Management in Arria V Devices
 Describes the power-up sequence required for Arria V GX and GT devices.

Adaptive Logic Module

Arria V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 7: ALM for Arria V Devices



You can configure up to 50% of the ALMs in the Arria V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Arria V Devices on page 20

Lists the embedded memory capacity for each device.



Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Mem ber	Variable- precision	Independ	ent Input and Ope	18 x 18 Multiplier	18 x 18 Multiplier Adder Summed			
Variant	Code	DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier	Adder Mode	with 36 bit Input	
	A1	240	720	480	240	_	240	240	
	A3	396	1,188	792	396	_	396	396	
	A5	600	1,800	1,200	600	_	600	600	
Arria V	A7	800	2,400	1,600	800	_	800	800	
GX	B1	920	2,760	1,840	920	_	920	920	
	В3	1,045	3,135	2,090	1,045	_	1,045	1,045	
	B5	1,092	3,276	2,184	1,092	_	1,092	1,092	
	B7	1,156	3,468	2,312	1,156	_	1,156	1,156	
	C3	396	1,188	792	396	_	396	396	
Arria V	C7	800	2,400	1,600	800	_	800	800	
GT	D3	1,045	3,135	2,090	1,045	_	1,045	1,045	
	D7	1,156	3,468	2,312	1,156	_	1,156	1,156	
	E1	800	2,400	1,600	800	400	800	800	
Arria V	E3	1,044	3,132	2,088	1,044	522	1,044	1,044	
GZ	E5	1,092	3,276	2,184	1,092	546	1,092	1,092	
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139	
Arria V	В3	809	2,427	1,618	809	_	809	809	
SX	B5	1,090	3,270	2,180	1,090	_	1,090	1,090	
Arria V	D3	809	2,427	1,618	809	_	809	809	
ST	D5	1,090	3,270	2,180	1,090	_	1,090	1,090	

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



Types of Embedded Memory

The Arria V devices contain two types of memory blocks:

- 20 Kb M20K or 10 Kb M10K blocks—blocks of dedicated memory resources. The M20K and M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Arria V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB. You can also configure these ALMs, in Arria V GZ devices, as ten 64 x 1 blocks, giving you one 64 x 10 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Arria V Devices

Table 16: Embedded Memory Capacity and Distribution in Arria V Devices

		M2	:0K	M1	0K	ML	.AB	
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
	A1	_	_	800	8,000	741	463	8,463
	A3	_	_	1,051	10,510	1538	961	11,471
	A5	_	_	1,180	11,800	1877	1,173	12,973
Arria V GX	A7	_	_	1,366	13,660	2317	1,448	15,108
Allia V GA	B1	_	_	1,510	15,100	2964	1,852	16,952
	В3	_	_	1,726	17,260	3357	2,098	19,358
	B5	_	_	2,054	20,540	4052	2,532	23,072
	В7	_	_	2,414	24,140	4650	2,906	27,046
	C3	_	_	1,051	10,510	1538	961	11,471
Arria V GT	C7	_	_	1,366	13,660	2317	1,448	15,108
Allia V GI	D3	_	_	1,726	17,260	3357	2,098	19,358
	D7	_	_	2,414	24,140	4650	2,906	27,046
	E1	585	11,700	_	_	4,151	2,594	14,294
Arria V GZ	E3	957	19,140	_	_	6,792	4,245	23,385
Allia V GZ	E5	1,440	28,800	_	_	7,548	4,718	33,518
	E7	1,700	34,000	_	_	8,490	5,306	39,306
Arria V SX	В3	_	_	1,729	17,290	3223	2,014	19,304
Allia v SA	B5	_	_	2,282	22,820	4253	2,658	25,478



		M20K		M10K		MLAB		
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Arrio V ST	D3	_	_	1,729	17,290	3223	2,014	19,304
Arria V ST	D5	_	_	2,282	22,820	4253	2,658	25,478

Embedded Memory Configurations

Table 17: Supported Embedded Memory Block Configurations for Arria V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
MLAD	64 ⁽¹¹⁾	x10
	512	x40
	1K	x20
M20K	2K	x10
WIZOK	4K	x5
	8K	x2
	16K	x1
	256	x40 or x32
	512	x20 or x16
M10K	1K	x10 or x8
WITOK	2K	x5 or x4
	4K	x2
	8K	x1

Clock Networks and PLL Clock Sources

650 MHz Arria V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Altera's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Quartus Prime software identifies all unused sections of the clock network and powers them down.



⁽¹¹⁾ Available for Arria V GZ devices only.

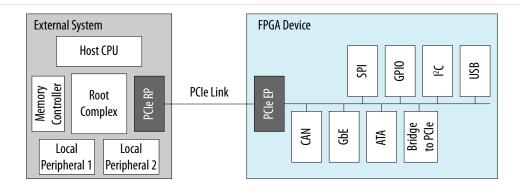
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.



Figure 9: Device Chip Overview for Arria V GX and GT Devices

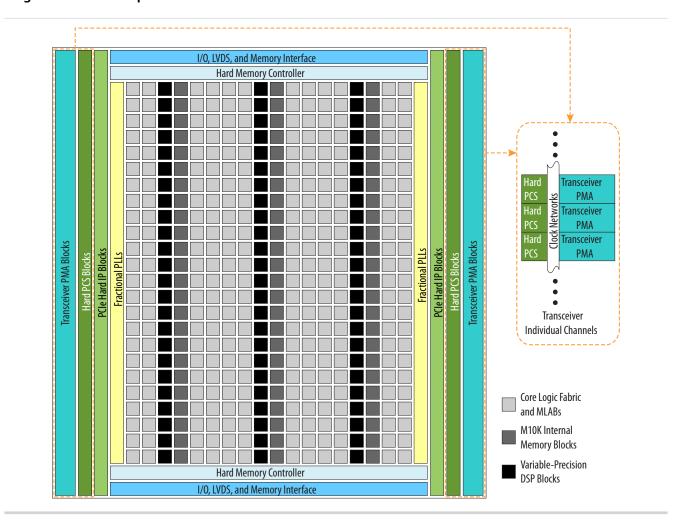
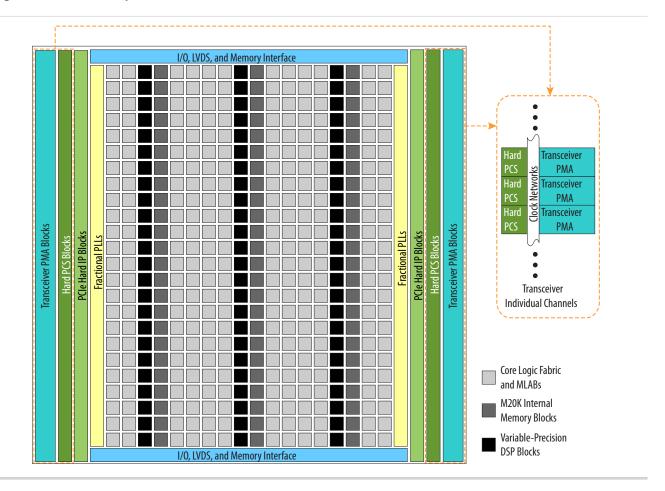




Figure 10: Device Chip Overview for Arria V GZ Devices





PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8) PCIe Gen2 ⁽¹⁴⁾ (x1, x2, x4)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder PIPE 2.0 interface to the core logic 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO PIPE 2.0 interface to the core logic
GbE	1.25	Phase compensation FIFOByte serializer8B/10B encoder	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO
XAUI ⁽¹⁵⁾	3.125	 Phase compensation FIFO Byte serializer 8B/10B encoder XAUI state machine for bonding four channels 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO XAUI state machine for realigning four channels Deskew FIFO circuitry
SDI	0.27 ⁽¹⁶⁾ , 1.485, 2.97	Phase compensation FIFO Byte serializer	Byte deserializerPhase compensation FIFO
GPON ⁽¹⁷⁾	1.25 and 2.5	byte serializer	1 mase compensation in O
CPRI ⁽¹⁸⁾	0.6144 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder TX deterministic latency 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO RX deterministic latency



⁽¹³⁾ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCIe Gen2 is supported only through the PCIe hard IP.

⁽¹⁵⁾ XAUI is supported through the soft PCS.

⁽¹⁶⁾ The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

 $^{^{\}left(17\right) }$ The GPON standard does not support burst mode.

⁽¹⁸⁾ CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet 100GBASE-R Ethernet	4 x 10.3125 10 x 10.3125	 TX FIFO 64B/66B encoder Scrambler Alignment marker insertion Gearbox Block stripper 	 RX FIFO 64B/66B decoder Descrambler Lane reorder Deskew Alignment marker lock Block synchronization Gear box Destripper
40G and 100G OTN	(4+1) x 11.3 (10+1) x 11.3	 TX FIFO Channel bonding Byte serializer	RX FIFOLane deskewByte deserializer
GbE	1.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding GbE state machine 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering GbE state machine
XAUI	3.125 to 4.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding XAUI state machine for bonding four channels 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding SRIO V2.1-compliant x2 and x4 channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering SRIO V2.1-compliant x2 and x4 deskew state machine



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXITM) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 533 MHz (1066 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.



Document Revision History

Date	Version	Changes
December 2015	2015.12.21	 Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
January 2015	2015.01.23	 Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Added link to Altera Product Selector for each device variant. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	 Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. Added transceiver speed grade 6 to the available options of the Arria V SX variant. Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.

